PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	MDG/23/13703
1.3 Title of PCN	ST Shenzhen (China) TSSOP20 package copper alloy bonding wire introduction on STM32G03x and STM32G04x listed products
1.4 Product Category	STM32G03x STM32G04x
1.5 Issue date	2023-01-22

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ST Shenzhen (China)

4. Description of change

	Old	**New**
4.1 Description	Wire bonding material: - ST Shenzhen (China) Silver alloy wire - Amkor ATP (Philippines) gold wire	Wire bonding material: - ST Shenzhen (China) Copper Alloy wire - Amkor ATP (Philippines) gold wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools

7. Timing / schedule

7.1 Date of qualification results	2023-03-28
7.2 Intended start of delivery	2023-04-06
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13703 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0 - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2023-01-22

9. Attachments (additional documentations)
13703 Public product.pdf 13703 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0 - reliability plan.pdf 13703 PCN13703_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G030F6P6	
	STM32G030F6P6TR	
	STM32G031F4P3	
	STM32G031F4P6	
	STM32G031F6P6	
	STM32G031F8P6	

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : ST Shenzhen (China) TSSOP20 package copper alloy bonding wire introduction on STM32G03x and STM32G04x listed products
PCN Reference : MDG/23/13703

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32G041F8P6	STM32G031F4P6	STM32G031F6P6
STM32G030F6P6	STM32G031F8P6	STM32G041F6P6
STM32G030F6P6TR	STM32G031F4P3	STM32G031F8P6TR
STM32G041F6P6TR	STM32G031F6P7TR	

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